

3.5x2.8mm SURFACE MOUNT LED LAMP



ATTENTION OBSERVE PRECAUTIONS FOR HANDLING **ELECTROSTATIC** DISCHARGE SENSITIVE **DEVICES**

Part Number: KAA-3528RGBS-11

Hyper Red Green Blue

Features

- Suitable for all SMT assembly and solder process.
- Available on tape and reel.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Hyper Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

The Green source color devices are made with InGaN on Sapphire Light Emitting Diode.

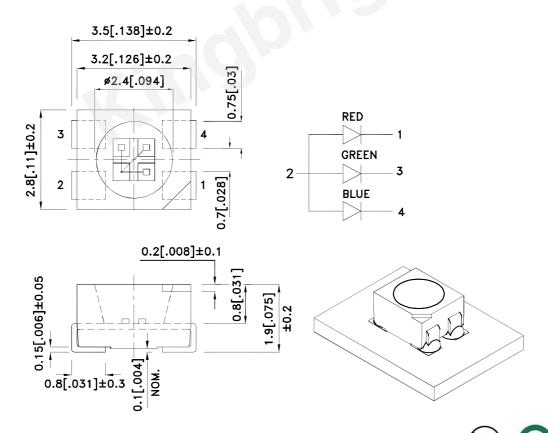
The Blue source color devices are made with InGaN Light Emitting Diode.

Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

 4. The device has a single mounting surface. The device must be mounted according to the specifications.

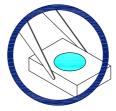
SPEC NO: DSAM4753 **REV NO: V.2B DATE: MAR/07/2013** PAGE: 1 OF 8 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: Y.Liu ERP: 1201008340

Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly Orangeuces thermal stress, it is more susceptible to damage by external mechanical force.

As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.



2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.





3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.

5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

Detailed application notes are listed on our website. http://www.kingbright.com/application notes

SPEC NO: DSAM4753 REV NO: V.2B DATE: MAR/07/2013 PAGE: 2 OF 8
APPROVED: WYNEC CHECKED: Allen Liu DRAWN: Y.Liu ERP: 1201008340

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
KAA-3528RGBS-11	Hyper Red (AlGaInP)		120	220	120°
	Green (InGaN)	Water Clear	400	500	
	Blue (InGaN)		55	100	

Notes:

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.
- 3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red Green Blue	630 515 468		nm	IF=20mA
λD [1]	Dominant Wavelength	Hyper Red Green Blue	621 525 470		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red Green Blue	20 30 25		nm	IF=20mA
С	Capacitance	Hyper Red Green Blue	25 45 100		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red Green Blue	2 3.3 3.3	2.5 4.1 4	V	IF=20mA
lr	Reverse Current	Hyper Red Green Blue		10 50 50	uA	V _R =5V

- Notes:
 1.Wavelength: +/-1nm.
 2. Forward Voltage: +/-0.1V.
 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

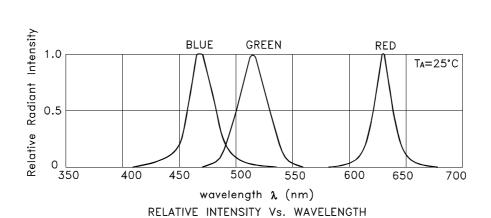
Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red	Green	Blue	Units		
Power dissipation	75	123	120	mW		
DC Forward Current	30	30	30	mA		
Peak Forward Current [1]	195	150	150	mA		
Reverse Voltage		V				
Operating Temperature	-40°C To +85°C					
Storage Temperature	-40°C To +85°C					

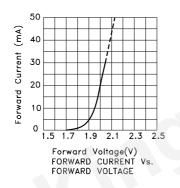
Notes:

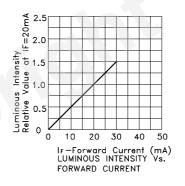
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

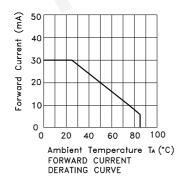
SPEC NO: DSAM4753 **REV NO: V.2B** DATE: MAR/07/2013 PAGE: 3 OF 8 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: Y.Liu ERP: 1201008340

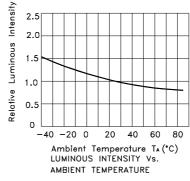


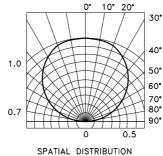
KAA-3528RGBS-11 Hyper Red







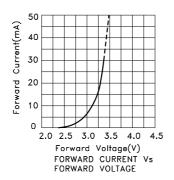


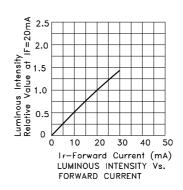


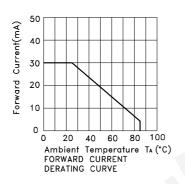
SI ATIAL DISTRIBUTION

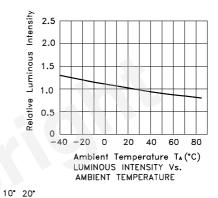
SPEC NO: DSAM4753 REV NO: V.2B DATE: MAR/07/2013 PAGE: 4 OF 8
APPROVED: WYNEC CHECKED: Allen Liu DRAWN: Y.Liu ERP: 1201008340

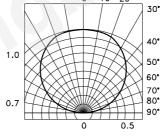
Green









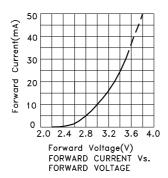


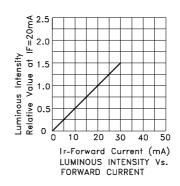
SPATIAL DISTRIBUTION

SPEC NO: DSAM4753 REV NO: V.2B DATE: MAR/07/2013 PAGE: 5 OF 8

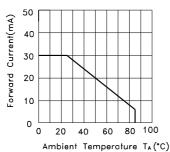
APPROVED: WYNEC CHECKED: Allen Liu DRAWN: Y.Liu ERP: 1201008340

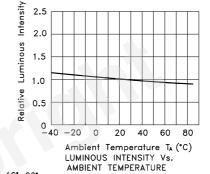
Blue

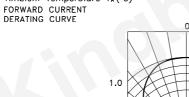


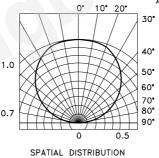


2.5









SPEC NO: DSAM4753 APPROVED: WYNEC

REV NO: V.2B CHECKED: Allen Liu

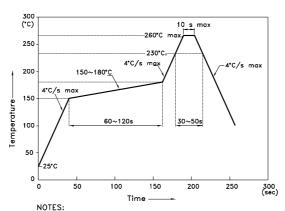
DATE: MAR/07/2013 DRAWN: Y.Liu

PAGE: 6 OF 8 ERP: 1201008340

KAA-3528RGBS-11

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



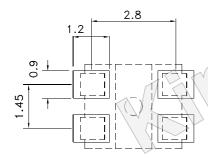
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.

 2.Don't cause stress to the epoxy resin while it is exposed to be the properture.
 - to high temperature.

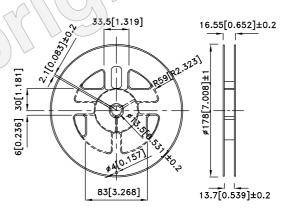
 3.Number of reflow process shall be 2 times or less.

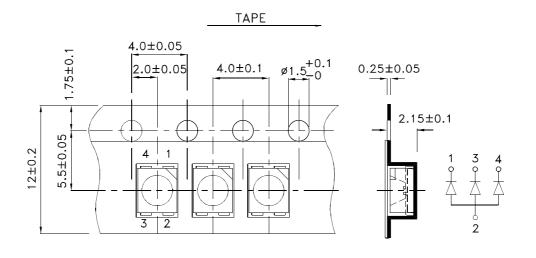
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Tape Dimensions (Units : mm)

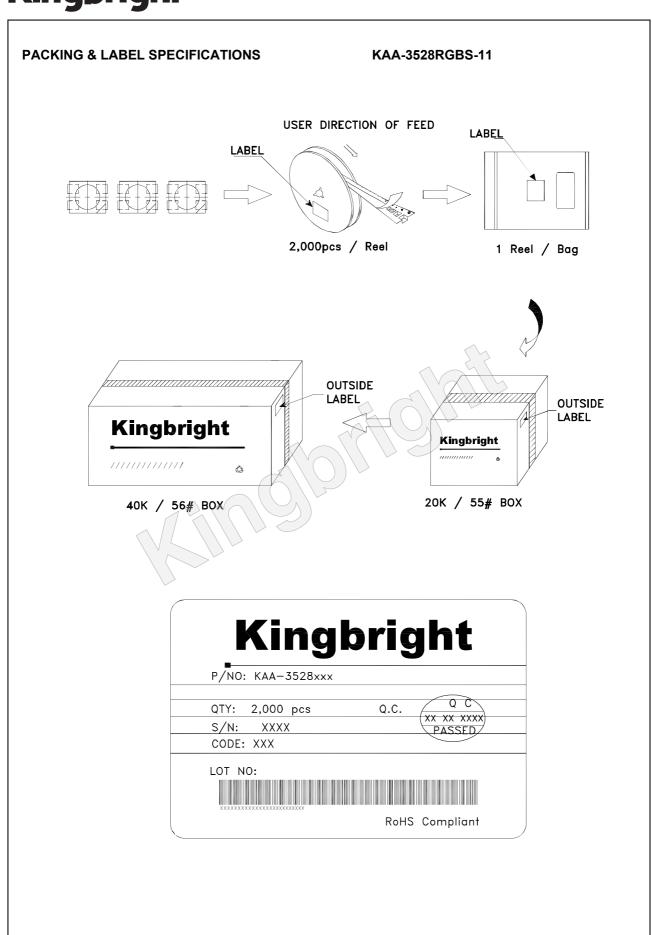
Reel Dimension





SPEC NO: DSAM4753 REV NO: V.2B DATE: MAR/07/2013 PAGE: 7 OF 8

APPROVED: WYNEC CHECKED: Allen Liu DRAWN: Y.Liu ERP: 1201008340



SPEC NO: DSAM4753 APPROVED: WYNEC REV NO: V.2B CHECKED: Allen Liu DATE: MAR/07/2013 DRAWN: Y.Liu PAGE: 8 OF 8 ERP: 1201008340